

12. (Newly Added) A method of forming a bump on a wafer for a structure device, comprising:

forming a bonding pad over the wafer;

forming a protection layer over the wafer, wherein the protection layer has an opening to expose a portion of the bonding pad, wherein a hillock still remains on the bonding pad;

performing a wet etching to at least remove the hillock on the bonding pad; and

forming a bump structure on the bonding pad.

13. The method of claim 12, wherein in the step of performing the wet etching, the bonding pad is etched to form a concave region.

REMARKS

Present Status of the Application

The Office Action rejected all presently-pending claims 1-11. Specifically, the Office Action rejected claims 1-11 under 35 U.S.C. 102, as being anticipated by Lin et al. (U. S. Patent 6,426,281). Applicants have amended specification and added claim 12-13 above. After entry of the foregoing amendments, claims 1-13 remain pending in the present application, and reconsideration of those claims is respectfully requested.

Summary of Applicant's Invention